

#### DMT6009LPS

# 60V N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI

#### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> T <sub>C</sub> = +25°C
60V	$10m\Omega$ @ $V_{GS} = 10V$	87A
60 V	$12m\Omega$ @ $V_{GS} = 4.5V$	79A

#### **Features**

- 100% Unclamped Inductive Switching Ensures More Reliable and Robust End Application
- Low R<sub>DS(ON)</sub> Minimizes Power Losses
- Low Q<sub>G</sub> Minimizes Switching Losses
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

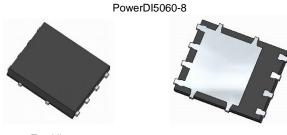
### **Description and Applications**

This MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>), yet maintain superior switching performance, making it ideal for high efficiency power management applications.

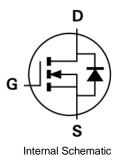
- High Frequency Switching
- · Sync. Rectification
- DC-DC Converters

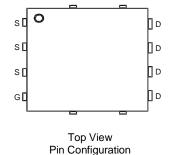
#### **Mechanical Data**

- Case: PowerDI<sup>®</sup>5060-8
- Case Material: Molded Plastic, "Green" Molding Compound.
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe.
  Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.097 grams (Approximate)



Top View Bottom View





#### Ordering Information (Note 4)

Part Number	Case	Packaging
DMT6009LPS-13	PowerDI5060-8	2,500/Tape & Reel

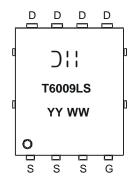
Notes:

1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

Pin1

- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## Marking Information



⊃¦¦ = Manufacturer's Marking T6009LS = Product Type Marking Code YYWW = Date Code Marking YY = Year (ex: 16 = 2016) WW = Week (01 - 53)



### **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Drain-Source Voltage		$V_{DSS}$	60	V
Gate-Source Voltage		$V_{GSS}$	±16	V
Continuous Drain Current (Note 5)	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	Ι <sub>D</sub>	10.6 9.1	Α
Continuous Drain Current (Note 6)	$T_C = +25$ °C $T_C = +70$ °C	ID	87 69	А
Maximum Continuous Body Diode Forward Current (Note 6)		I <sub>S</sub>	100	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)		I <sub>DM</sub>	160	Α
Avalanche Current, L=0.1mH		I <sub>AS</sub>	20.3	Α
Avalanche Energy, L=0.1mH		Eas	20.6	mJ

### **Thermal Characteristics**

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)	$T_A = +25$ °C	$P_{D}$	2.3	W
Thermal Resistance, Junction to Ambient (Note 5)		$R_{\theta JA}$	53	°C/W
Total Power Dissipation (Note 6)	T <sub>C</sub> = +25°C	$P_D$	113	W
Thermal Resistance, Junction to Case (Note 6)		$R_{ heta JC}$	1.1	°C/W
Operating and Storage Temperature Range		$T_{J_i}T_{STG}$	-55 to +150	°C

### Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	60	_	_	V	$V_{GS} = 0V$ , $I_D = 1mA$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	1	μΑ	$V_{DS} = 48V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 16V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	0.7	_	2	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance	D	_	7.2	10	mΩ	$V_{GS} = 10V, I_D = 20A$	
Static Dialii-Source Off-Resistance	R <sub>DS(ON)</sub>	_	8.9	12	11122	$V_{GS} = 4.5V, I_D = 15A$	
Diode Forward Voltage	$V_{SD}$	_	0.9	_	V	$V_{GS} = 0V, I_{S} = 20A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C <sub>ISS</sub>	_	1,925	_		$V_{DS} = 30V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Output Capacitance	Coss	_	438	_	pF		
Reverse Transfer Capacitance	$C_{RSS}$	_	41	_			
Gate Resistance	R <sub>G</sub>	_	1.7	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = 10V)	$Q_{G}$	_	33.5	_		V <sub>DS</sub> = 30V, I <sub>D</sub> = 13.5A	
Total Gate Charge (V <sub>GS</sub> = 4.5V)	$Q_G$	_	15.6	_	nC		
Gate-Source Charge	$Q_{GS}$	_	4.7	_	110		
Gate-Drain Charge	$Q_GD$	_	5.3	_			
Turn-On Delay Time	t <sub>D(ON)</sub>	_	4.5	_		$V_{DD} = 30V, V_{GS} = 10V,$ $R_G = 6\Omega, I_D = 13.5A$	
Turn-On Rise Time	t <sub>R</sub>	_	8.6		20		
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	35.9	_	ns		
Turn-Off Fall Time	t <sub>F</sub>	_	15.7	_			
Body Diode Reverse Recovery Time	t <sub>RR</sub>	_	18.2	_	ns	1 40.54 41/41 4004/	
Body Diode Reverse Recovery Charge	Q <sub>RR</sub>	_	33.1	_	nC	$I_F = 13.5A$ , di/dt = 400A/ $\mu$ s	

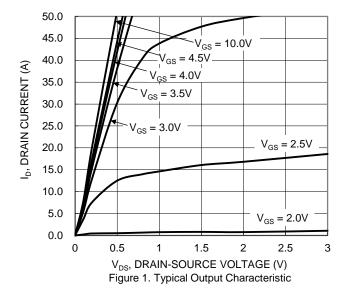
Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.

<sup>6.</sup> Thermal resistance from junction to soldering point (on the exposed drain pad).

<sup>7.</sup> Short duration pulse test used to minimize self-heating effect.

<sup>8.</sup> Guaranteed by design. Not subject to product testing.





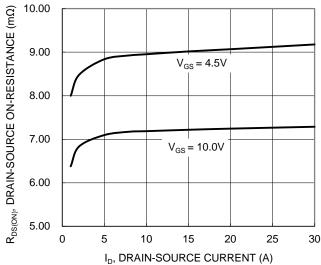


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

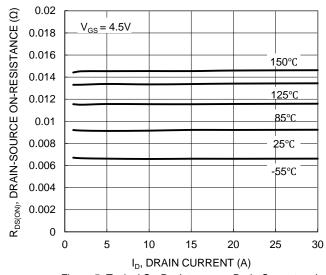


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

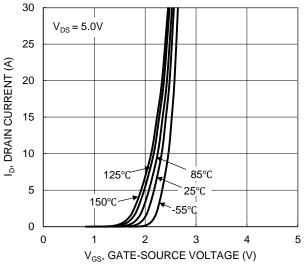
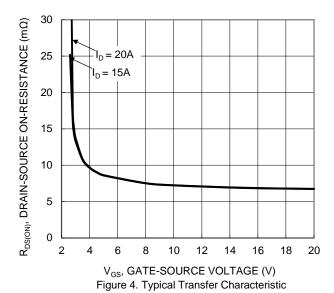


Figure 2. Typical Transfer Characteristic



2.2 R<sub>DS(ON)</sub>, DRAIN-SOURCE ON-RESISTANCE (NORMALIZED) 2 1.8 1.6  $V_{GS} = 4.5V, I_D = 15A$ 1.4 1.2 1  $V_{GS} = 10V, I_{D} = 20A$ 8.0 0.6 0.4 -50 -25 0 25 50 75 125 150 100

 $\label{eq:TJ} T_J, JUNCTION TEMPERATURE~(^{\circ}C)$  Figure 6. On-Resistance Variation with Temperature



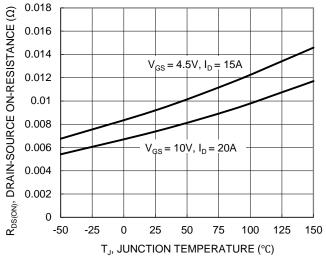
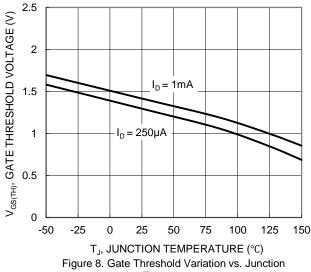


Figure 7. On-Resistance Variation with Temperature



Temperature

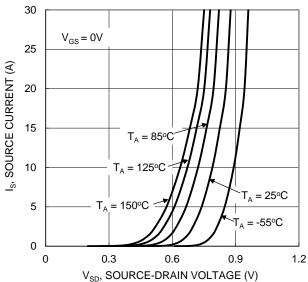


Figure 9. Diode Forward Voltage vs. Current

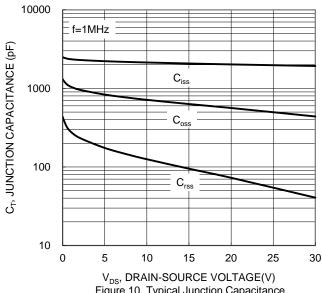


Figure 10. Typical Junction Capacitance

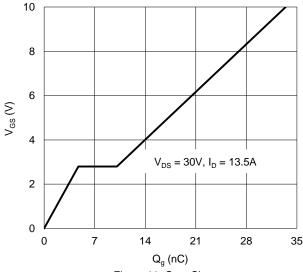


Figure 11. Gate Charge

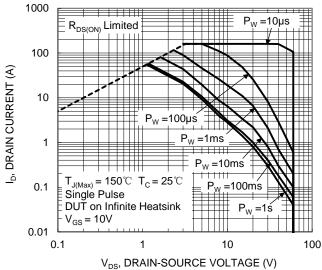


Figure 12. SOA, Safe Operation Area



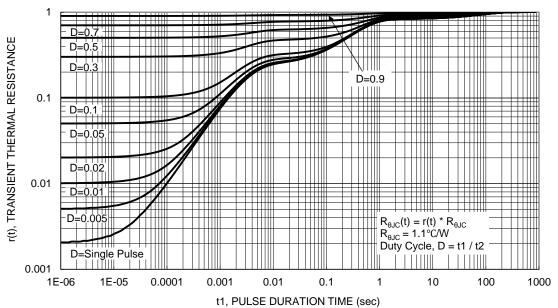


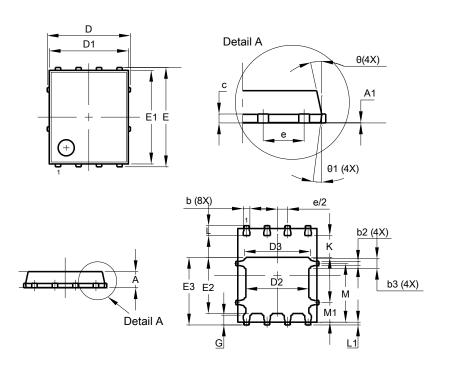
Figure 13. Transient Thermal Resistance



### **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI5060-8

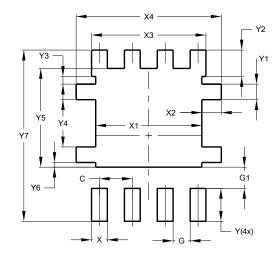


PowerDI5060-8					
Dim	Min	Max	Тур		
Α	0.90	1.10	1.00		
A1	0.00	0.05	_		
b	0.33	0.51	0.41		
b2	0.200	0.350	0.273		
b3	0.40	0.80	0.60		
С	0.230	0.330	0.277		
D		5.15 BSC	;		
D1	4.70	5.10	4.90		
D2	3.70	4.10	3.90		
D3	3.90	4.30	4.10		
Е	(	3.15 BSC	;		
E1	5.60	6.00	5.80		
E2	3.28	3.68	3.48		
E3	3.99	4.39	4.19		
е	1.27 BSC				
G	0.51	0.71	0.61		
K	0.51	ı	_		
L	0.51	0.71	0.61		
L1	0.100	0.200	0.175		
M	3.235	4.035	3.635		
M1	1.00	1.40	1.21		
θ	10°	12°	11°		
θ1	6°	8°	7°		
All Dimensions in mm					

### **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI5060-8



Dimensions	Value (in mm)			
С	1.270			
G	0.660			
G1	0.820			
Χ	0.610			
X1	4.100			
X2	0.755			
Х3	4.420			
X4	5.610			
Υ	1.270			
Y1	0.600			
Y2	1.020			
Y3	0.295			
Y4	1.825			
Y5	3.810			
Y6	0.180			
<b>Y</b> 7	6.610			



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